

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Hiroyuki OTAKI | 09/26/2011 |
| Kenji UEDA | 09/30/2011 |
| RECEIVING PARTY DATA | |
| Name: | DAI NIPPON PRINTING CO., LTD. |
| Street Address: | 1-1 ICHIGAYA-KAGACHO 1-CHOME, SHINJUKU-KU |
| City: | TOKYO-TO |
| State/Country: | JAPAN |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 13209513 |
| CORRESPONDENCE DATA | |
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| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Correspondent Name: | RICHARD J. STREIT |
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| Address Line 4: | CHICAGO, ILLINOIS 60604 |
| ATTORNEY DOCKET NUMBER: | CU-9287 EDB/CM |
| NAME OF SUBMITTER: | Zareefa B. Flener |
| Total Attachments: 2 source=cu9287_assignment#page1.tif source=cu9287_assignment#page2.tif | |

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PATENT
REEL: 027109 FRAME: 0153

UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

Hiroyuki OTAKI
c/o Dai Nippon Printing Co., Ltd.,
1-1 Ichigaya-kagacho 1-chome, Shinjuku-ku
Tokyo-to, Japan

Kenji UEDA
c/o Dai Nippon Printing Co., Ltd.,
1-1 Ichigaya-kagacho 1-chome, Shinjuku-ku
Tokyo-to, Japan

hereby sells, assigns and transfers to

ASSIGNEE:

DAI NIPPON PRINTING CO., LTD.
1-1 Ichigaya-kagacho 1-chome, Shinjuku-ku
Tokyo-to, Japan

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled VOLUME HOLOGRAM RESIN COMPOSITION, SURFACE RELIEF HOLOGRAM RESIN COMPOSITION, AND HOLOGRAM LAYER, HOLOGRAM TRANSFER FOIL AND BRITTLE HOLOGRAM LABEL USING THE SAME which application was

☐ (a) executed by the undersigned on _____

☒ (b) filed as Serial No. 13/209,513 on Aug. 15, 2011

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, we have set our hand and seal

26/09/2011

Date

Hiroyuki Otaki

Hiroyuki OTAKI

30/09/2011

Date

Kenji Ueda

Kenji UEDA

0699P/1 (U.S. rights)